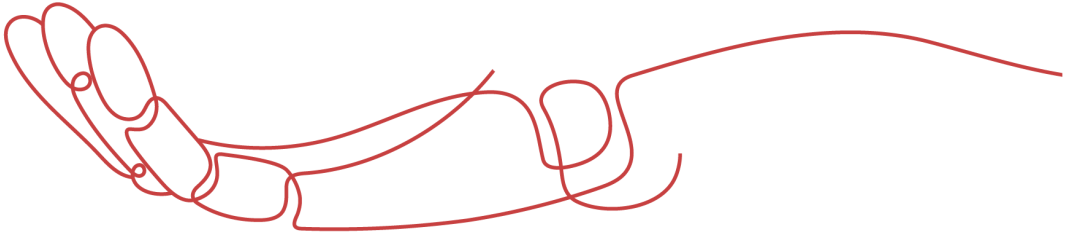




PRODUCT DATA SHEET



To learn more about JGSEMI, please visit our website at



Datasheet



Resources

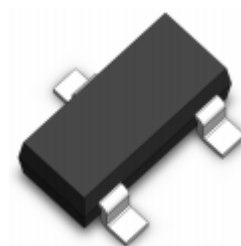


Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

Features

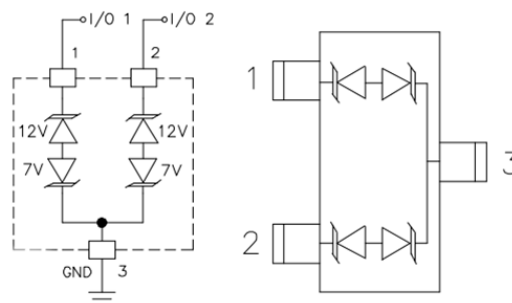
- Ultra low leakage: nA level
- Operating voltage: 7V or 12V
- Low clamping voltage
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 - Air discharge: $\pm 30\text{kV}$
 - Contact discharge: $\pm 30\text{kV}$
 - IEC61000-4-4 (EFT) 40A (5/50ns)
 - IEC61000-4-5 (Lightning) 12A (8/20 μs)
- RoHS Compliant



SOT-23

Applications

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)
- Notebook Computers
- SIM Ports
- 10/100 Ethernet



Mechanical Characteristics

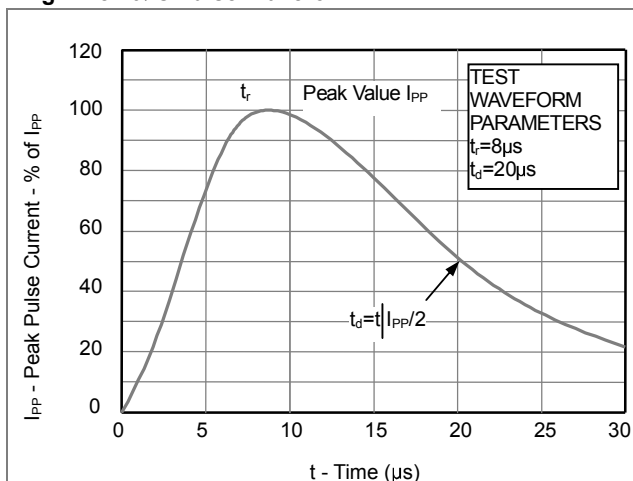
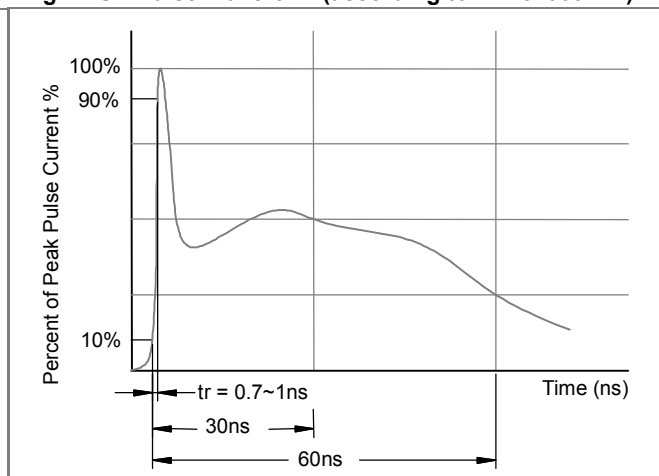
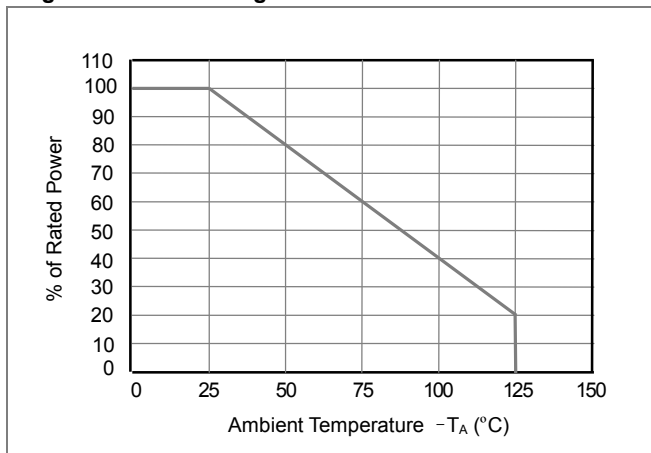
- Package: SOT-23
- Lead Finish: Lead Free
- UL Flammability Classification Rating 94V-0
- Quantity Per Reel: 3,000 pcs
- Reel Size: 7 inch

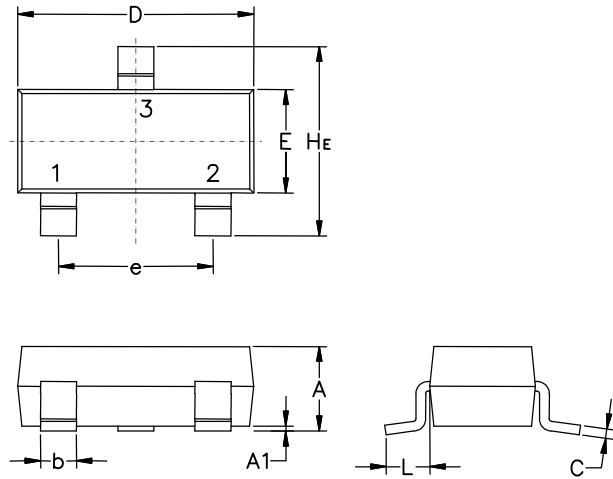
Absolute Maximum Ratings (T_{amb}=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20 μs)	P _{pp}	400	W
ESD per IEC 61000-4-2 (Air)	V _{ESD}	± 30	Kv
ESD per IEC 61000-4-2 (Contact)		± 30	
Operating Temperature Range	T _J	-55 to +125	°C
Storage Temperature Range	T _{STJ}	-55 to +150	°C

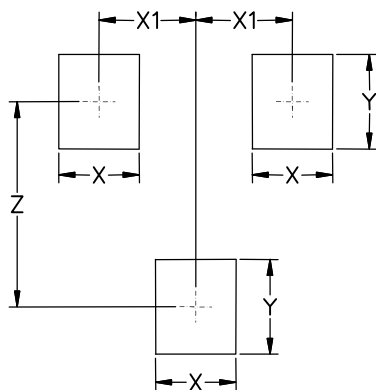
Electrical Characteristics(TA=25°C unless otherwise specified)

Part Number	V _{BR} (V)	I _T (mA)	V _C @1A	V _C		I _R μA (Max)	C (Pf) (Typ.)
				(Max)	(@A)		
BST23C712V	7.5	1	10	12	17	10	45
	13.3	1	20	26	17	1	45

Characteristic Curves
Fig1. 8/20μs Pulse Waveform

Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

Fig3. Power Derating Curve


SOT-23 Package Outline & Dimensions


Symbol	Millimeters			Inches		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.15	0.18	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.35	0.54	0.69	0.014	0.021	0.029
H _E	2.10	2.40	2.64	0.083	0.094	0.104

Soldering Footprint


Symbol	Millimeters	Inches
X	0.80	0.031
X1	0.95	0.037
Y	0.90	0.035
Z	2.00	0.079

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